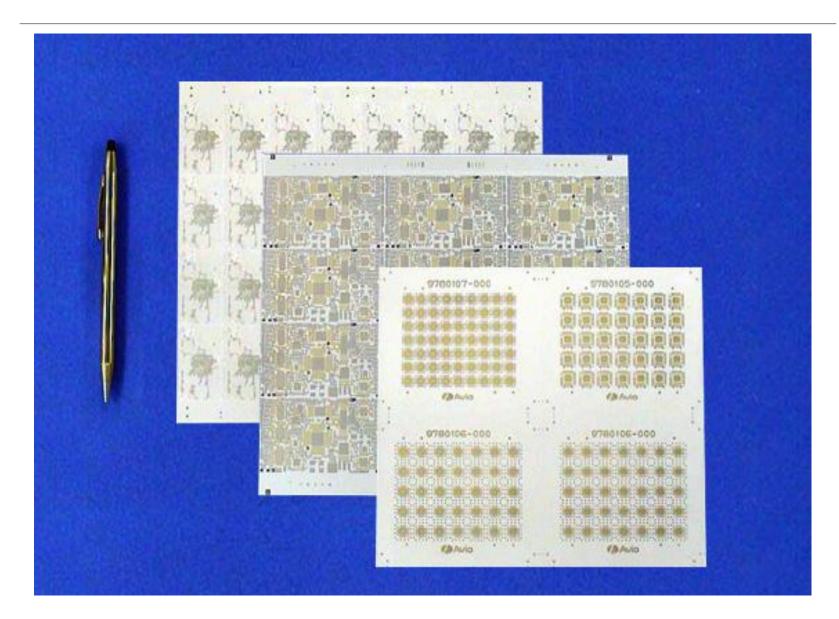


Low temperature Co-fired Ceramics.



This is muRata's exotic LTCC





What is LTCC?



"LTCC" stands for Low Temperature Co-fired Ceramics

	muRata LTCC	нтсс
Major Materials	Glass + Alumina	Alumina
Conductor & Via Materials	Ag	W or Mo
Firing (Sintering) Temperature	Below 1,000°C	1,500 ~ 1,600°C
Features	✓ Excellent high frequency signal transmission – Ag via✓ Zero Shrink sintering	✓ High thermal Conductivity

Features

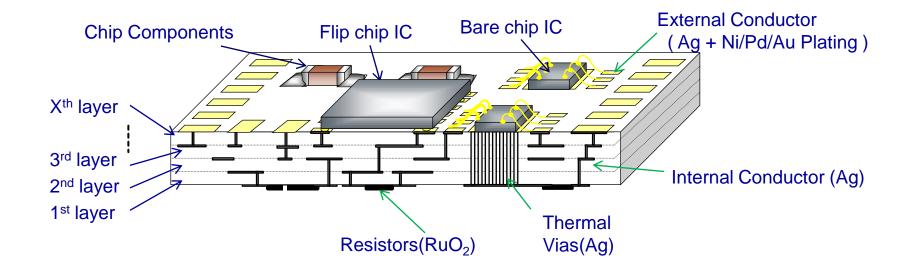
- Large size panel
- High Dimensional Accuracy
- Plating available
- Embedded passive functions
- Resistor printing

Ni-Pd-Au or Ni-Au electroless plating
$$\sim$$
100pF、 \sim 100nH

Accuracy $\pm 1\%$ after trimming, TCR \pm 100ppm, 20-100K Ω square

LTCC Outline





- ✓ LTCC Material: Composite of Glass(CaO-Al₂O₃-B₂O₃-SiO₂) & Alumina(Al₂O₃)
- ✓ Features: Low Temperature Firing (< 900°C, Alumina=1,500°C)

 Inner electrode is Ag.

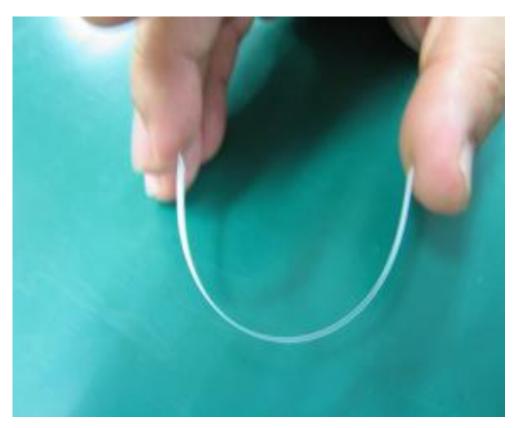
Ag filled thermal via.

Surface electrode is Ag+ Ni/(Pd)/Au electroless plating.

Non hazardous materials like Pb, Cd, Hg, etc.

Seeing is believing





0.075mm t (5mm W x 100mm L)

Comparison – vs Alumina



✓ None shrinkage firing vs shrinkage firing

Murata LTCC **HTCC** shrinkage firing none shrinkage firing Non shrinkage firing Non Constraint firing ✓ Substrates shrink by about 20% in X&Y direction. ✓ No shrinkage of panel areas in X&Y but about 50% in Z direction. ✓ Dimensions will become 60% of original size. Same electrode dimensions as printed. Green sheet Fired substrate Green sheet Fired substrate Shrink Same size Dimensional Accuracy after firing: +/-0.1% Dimensional Accuracy after firing: +/-0.5% Flatness after firing: Excellent Flatness after firing: Poor Green sheet size: Large-8"x8" Green sheet size: small-around 4"x4"

Typical Application

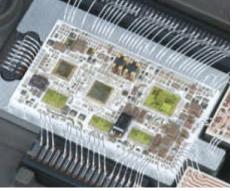




Automotive Power Train







LFC for ESC(1"x2")







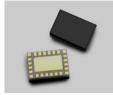




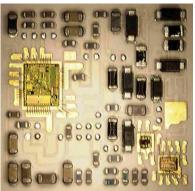




Communication device





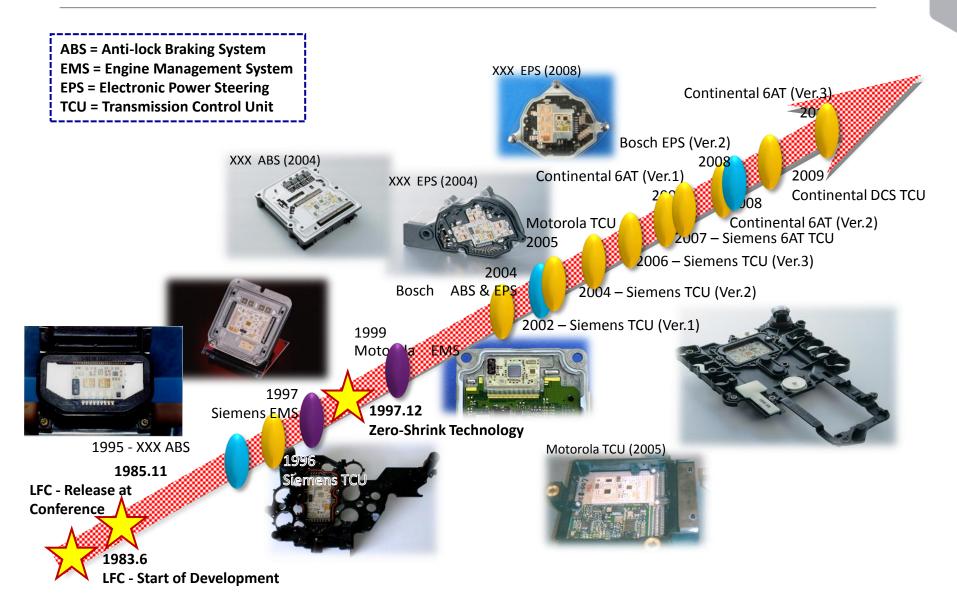


AWG for FEM(10x10mm)

AWG→ Alumina Wollastonite Glass

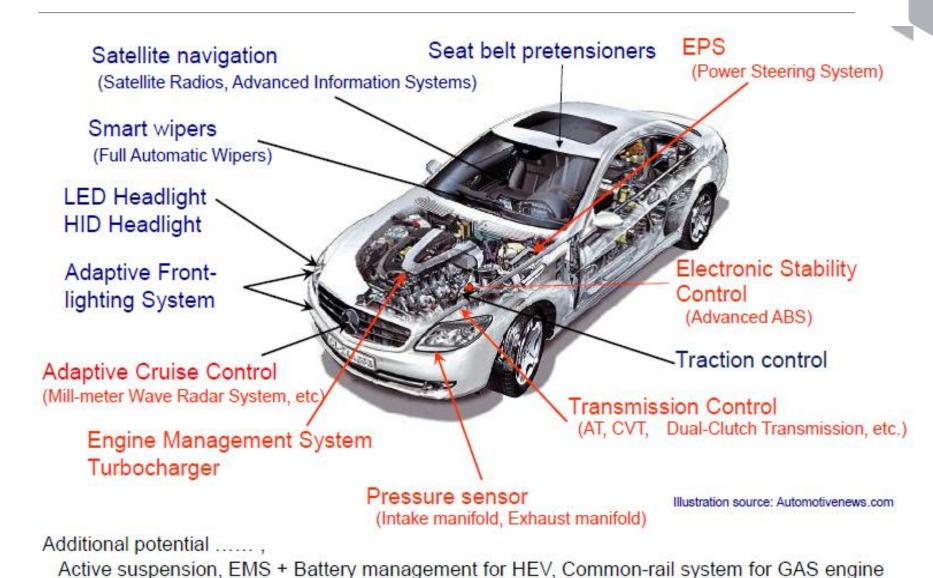
History of Automotive application (LFC)





Potential Applications in Car Electronics





LTCC Substrate technology



- Already having business with Continental for TCU application.
- Many possibilities to utilize such cutting edge technology for non power train applications like:
 - HID unit, radar/ Antenna modules,..etc (RF Applications)
 - → Miniaturization, High integration, robust performance.



Thank you very much for your attention!

